

Patent Abstracts of Japan

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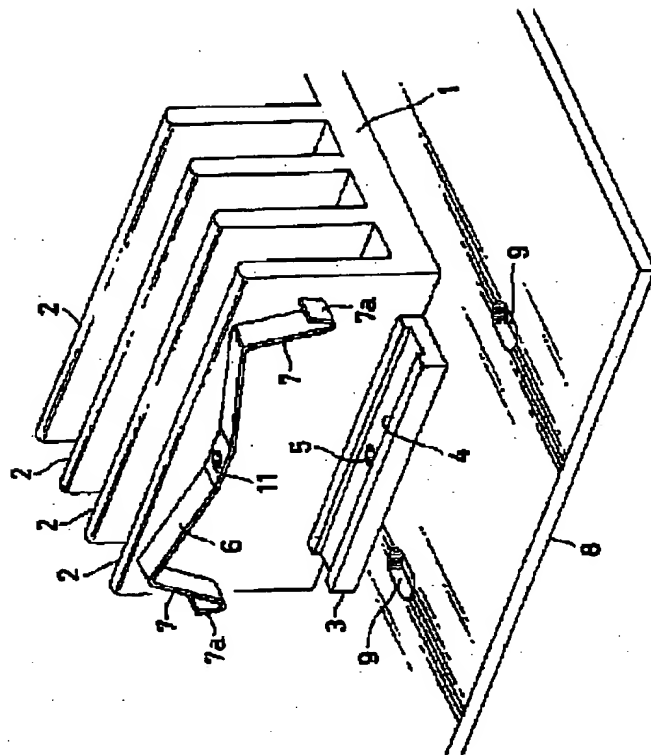
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TITLE : METHOD FOR FIXING HEAT SINK TO
PRINTED BOARD, HEAT SINK USED
THEREFOR AND CLIP FOR FIXING
THE SAME



ABSTRACT : PROBLEM TO BE SOLVED: To fix a heat sink to a printed board by using a clip having elasticity for itself, by engaging a center of the clip made of an elastic material within a groove of a protruding edge of the sink, and inserting ends of both legs of the clip into holes opened at predetermined positions of a printed board.

SOLUTION: A heat sink is placed on a semiconductor unit mounted on a printed board 8, and lower ends of legs 7 of a clip 6 are passed through holes 9 of the board 8 while bending the clip 6 to its inside against its energizing direction. A center of the clip 6 is engaged with a groove 4 of a protruding edge 3 of the sink, and its boss 11 is engaged with a central hole 5 of the groove 4 of the edge 3 of the sink. When an elasticity of the clip 6 is returned to its energizing direction, the sink is fixed to the board 8 by an elastic force of the clip 6. Thus, the sink can be effectively fixed to the board via the clip, and can be simply detached or attached.

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